

**AT&S**Austria Technologie & Systemtechnik  
Aktiengesellschaft

# Press release

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### IPC awards research paper of AT&S-led EU Hermes Project

At IPC APEX EXPO™ in Las Vegas, the contribution of the Hermes Project to chip embedding technology was recognised with a “Best International Conference Paper” award. The research paper, entitled “Industrial PCB Development Using Embedded Passive & Active Discrete Chips Focused on Process and DfR”, is the result of close collaboration between Thales Corporate Services and AT&S as part of the EU-funded Hermes Project.

The focus of the prize-winning paper is on the technical options for chip embedding and on reliability – subjects under investigation in the Hermes Project. In the past 15 years, AT&S has established a worldwide reputation in the industry as a technology leader in miniaturisation. AT&S’s partners in the EU-funded Hermes Project include major international industrial, automotive and aerospace players. The main purpose of the new technology is to enhance the performance of printed circuit boards by using embedded chips to integrate additional functions. Another focus is on the design and organisation of the value chain, which puts manufacturers in a position to meet future technical and organisational requirements.

As part of the annual APEX EXPO™ event, IPC awards prizes for the best papers presented in the technical part of the conference; this year in early April, there were awards for the two best papers from the USA and the two best international papers. The prize-winning paper and related pictures of the event can be downloaded from the Hermes website at [www.hermes-ect.net](http://www.hermes-ect.net).

#### About Hermes

The Hermes Project (**H**igh density integration by **E**MBEDDED chips for **R**EDUCED sized **M**ODULES and **E**LECTRONIC **S**YSTEMS) was launched by AT&S and is funded by the EU. It involves research into the next technological advance in printed circuit boards – a new packaging solution for semiconductors that takes connectivity far beyond what is presently possible. Industrial implementation of this technology opens up a wide range of potential applications in medicine (e.g., a new generation of hearing aids) and in functional modules such as GPS. The future of mobile devices lies in enhanced performance and the integration of additional functions, and the Hermes Project is intended to make such an improvement in performance possible. For more information visit [www.hermes-ect.net](http://www.hermes-ect.net)

#### About AT&S

AT&S Austria Technologie & Systemtechnik Aktiengesellschaft (AT&S) is European market leader and one of the world’s strongest-performing printed circuit board manufacturers. AT&S is especially well positioned worldwide in the high-tech market segment for HDI microvia printed circuit boards, which are chiefly used in mobile devices. The Group is also highly successful in the automotive printed circuit board market, and in the industrial and medical technology sectors. As a vigorous and growing international enterprise, AT&S has a global presence, with three production facilities in Austria (Leoben, Fehring, Klagenfurt) and one each in India (Nanjangud), China (Shanghai) and Korea (Ansan, near Seoul). For more information visit [www.ats.net](http://www.ats.net)

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